

## ABSTRACT

Provided in the present disclosure are a coil, a coil assembly, a coil device, and an inductively coupled plasma semiconductor process apparatus. The coil extends on  
5 a plane by gyration. The coil includes a plurality of arched parts and a plurality of connection parts arranged about a gyration center of the coil. The coil has a first end and a second end, where from the first end to the second end of the coil, the arched parts and the connection parts are sequentially and alternately arranged at intervals, and gyration radii of the arched parts gradually increase. At least one of the plurality  
10 of arched parts includes a first deformable segment, an arc segment and a second deformable segment connected in sequence. According to the coil of the present disclosure, by providing the first deformable segment and the second deformable segment on the arched part, an area difference generated on the coil to avoid terminal studs can be counteracted, and a more uniform plasma density distribution over a wafer  
15 can be achieved.